IEEE FLEPS 2027

IEEE International Conference on Flexible, Printable Sensors and Systems

Cambridge, UK // July 11-14, 2027



CALL FOR PAPERS

IMPORTANT DATES

January 31, 2027
Focus Sessions Proposals Submission Deadline

February 14, 2027
Option B: Submit to IEEE Sensors Letters

March 7, 2027
Option A: Submit to IEEE FLEPS 2027 Proceedings

March 28, 2027
Tutorial/Workshop Proposals Submission Deadline

April 18, 2027
Notification of Outcome

May 9, 2027
Final Manuscript Submission Deadline

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Loughborough University, UK

Emre Ozer
Pragmatic Semiconductor, UK

Local Organising Chair

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University of Cambridge, UK

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The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2027) will be held in Cambridge, UK. IEEE FLEPS 2027 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

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TOPICS OF INTEREST

- Organic/Inorganic Electronics and Sensors
- Materials and Design for Flexible, Stretchable, and Printed Systems
- Advanced Manufacturing Techniques
- High-throughput Printable Electronics
- Hybrid Systems and Heterogeneous Integration
- Stretchable/Shrinkable Sensors and Electronics
- Wearable and Implantable Systems
- Degradable/Reusable Sensors and Systems
- Printed Large-Area Sensors and Systems
- Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- Emerging applications of Flexible Electronics in AI, Robotics, Cognitive Systems, IoT, smart cities etc.
- Reliability, Simulation and Modelling
- Circular/Sustainable Electronics Using Beneficial Materials and Processes
- Standards for Flexible and Stretchable Electronics
- Flexible and Printed Integrated Circuits (ICs)
- Machine Learning for Flexible Electronic Materials Discovery and Design

For further information, contact **Sara Diffenbach** at Conference Catalysts, LLC.

IEEE Sensors Council

IEEE Technical Committee on FLEPS
Flexible Printed Sensors and Systems

INTERESTED TO JOIN TC FLEPS?

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